



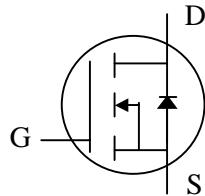
## N-channel Enhancement-mode Power MOSFET

**Simple Drive Requirement**

**Low Gate Charge**

**Fast Switching Performance**

**RoHS-compliant**

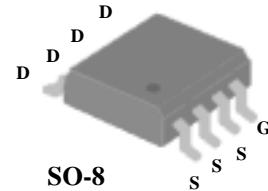


$BV_{DSS}$	60V
$R_{DS(ON)}$	40mΩ
$I_D$	6.9A

## Description

Advanced Power MOSFETs from APEC provide the designer with the best combination of fast switching, low on-resistance and cost-effectiveness.

The AP9475GM-3 is in the SO-8 package, which is widely used for commercial and industrial surface-mount applications, and is well suited for low voltage applications such as DC/DC converters.



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	60	V
$V_{GS}$	Gate-Source Voltage	$\pm 25$	V
$I_D$ at $T_A=25^\circ\text{C}$	Continuous Drain Current <sup>3</sup>	6.9	A
$I_D$ at $T_A= 70^\circ\text{C}$	Continuous Drain Current <sup>3</sup>	5.5	A
$I_{DM}$	Pulsed Drain Current <sup>1</sup>	30	A
$P_D$ at $T_A=25^\circ\text{C}$	Total Power Dissipation	2.5	W
	Linear Derating Factor	0.02	W/ $^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

## Thermal Data

Symbol	Parameter	Value	Unit
$R_{thj-a}$	Maximum Thermal Resistance, Junction-ambient	50	$^\circ\text{C/W}$

## Ordering Information

**AP9475GM-3TR RoHS-compliant halogen-free SO-8, shipped on tape and reel (3000 pcs/reel)**



**Electrical Specifications at  $T_j=25^\circ\text{C}$  (unless otherwise specified)**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=1\text{mA}$	60	-	-	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_j$	Breakdown Voltage Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	-	0.073	-	$\text{V}/^\circ\text{C}$
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=10\text{V}$ , $I_D=6\text{A}$	-	-	40	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$ , $I_D=4\text{A}$	-	-	50	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$ , $I_D=250\text{\mu A}$	1	-	3	V
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=10\text{V}$ , $I_D=6\text{A}$	-	10	-	S
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=60\text{V}$ , $V_{\text{GS}}=0\text{V}$	-	-	1	$\text{\mu A}$
	Drain-Source Leakage Current ( $T_j=70^\circ\text{C}$ )	$V_{\text{DS}}=48\text{V}$ , $V_{\text{GS}}=0\text{V}$	-	-	25	$\text{\mu A}$
$I_{\text{GSS}}$	Gate-Source Leakage	$V_{\text{GS}}=\pm 25\text{V}$ , $V_{\text{DS}}=0\text{V}$	-	-	$\pm 100$	nA
$Q_g$	Total Gate Charge <sup>2</sup>	$I_D=6\text{A}$	-	19	30	nC
$Q_{\text{gs}}$	Gate-Source Charge	$V_{\text{DS}}=48\text{V}$	-	5	-	nC
$Q_{\text{gd}}$	Gate-Drain ("Miller") Charge	$V_{\text{GS}}=4.5\text{V}$	-	10	-	nC
$t_{\text{d(on)}}$	Turn-on Delay Time <sup>2</sup>	$V_{\text{DS}}=30\text{V}$	-	11	-	ns
$t_r$	Rise Time	$I_D=1\text{A}$	-	6	-	ns
$t_{\text{d(off)}}$	Turn-off Delay Time	$R_G=3.3\Omega$ , $V_{\text{GS}}=10\text{V}$	-	35	-	ns
$t_f$	Fall Time	$R_D=30\Omega$	-	10	-	ns
$C_{\text{iss}}$	Input Capacitance	$V_{\text{GS}}=0\text{V}$	-	1670	2670	pF
$C_{\text{oss}}$	Output Capacitance	$V_{\text{DS}}=25\text{V}$	-	160	-	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance	f=1.0MHz	-	116	-	pF
$R_g$	Gate Resistance	f=1.0MHz	-	1.58	-	$\Omega$

**Source-Drain Diode**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_{\text{SD}}$	Forward On Voltage <sup>2</sup>	$I_S=2\text{A}$ , $V_{\text{GS}}=0\text{V}$	-	-	1.2	V
$t_{\text{rr}}$	Reverse Recovery Time <sup>2</sup>	$I_S=6\text{A}$ , $V_{\text{GS}}=0\text{V}$ ,	-	34	-	ns
$Q_{\text{rr}}$	Reverse Recovery Charge	dl/dt=100A/ $\mu\text{s}$	-	50	-	nC

**Notes:**

1. Pulse width limited by maximum junction temperature.
2. Pulse test - pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$
3. Surface mounted on 1 in<sup>2</sup> copper pad of FR4 board; 125°C/W on minimum copper pad.

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

APEC DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

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## Typical Electrical Characteristics

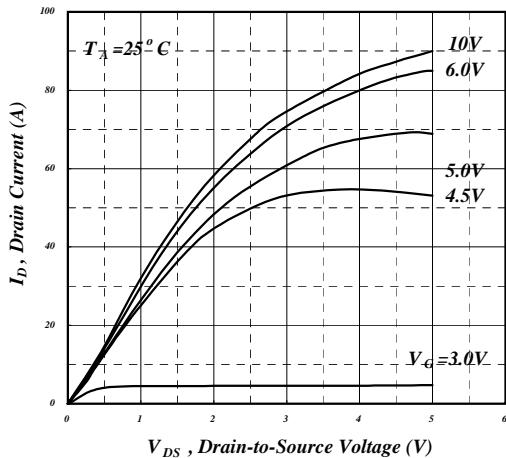


Fig 1. Typical Output Characteristics

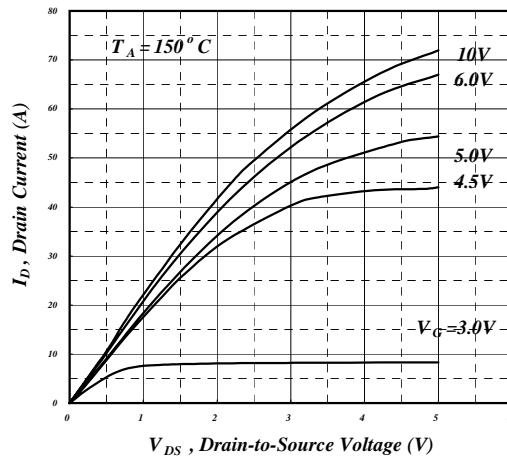


Fig 2. Typical Output Characteristics

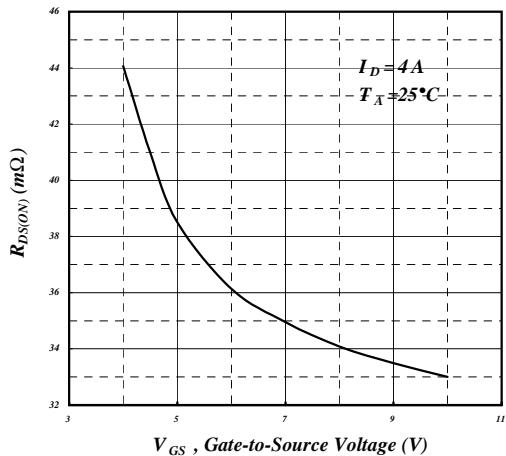


Fig 3. On-Resistance vs. Gate Voltage

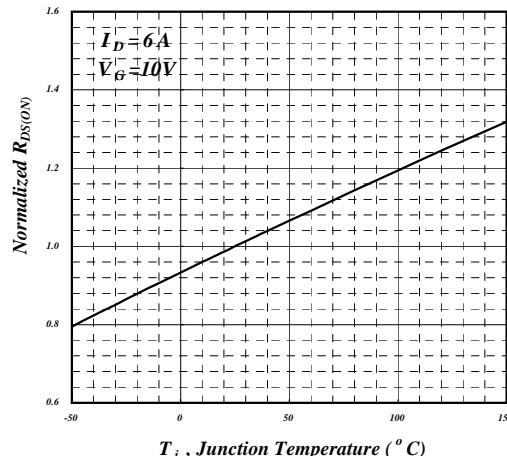


Fig 4. Normalized On-Resistance vs. Junction Temperature

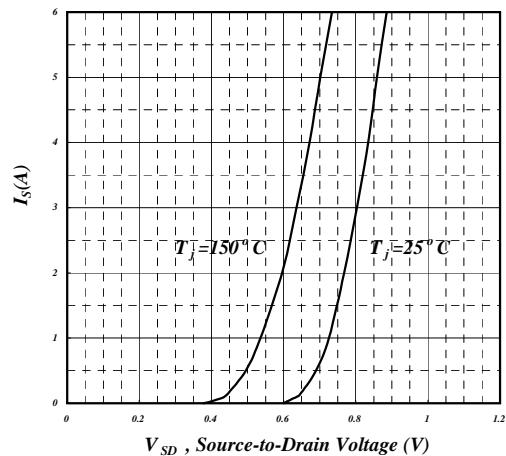


Fig 5. Forward Characteristic of Reverse Diode

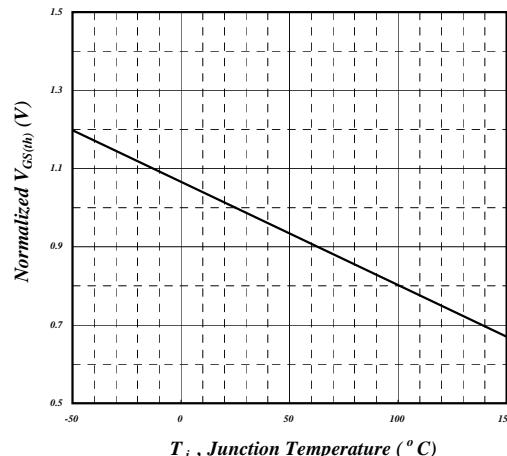


Fig 6. Gate Threshold Voltage vs. Junction Temperature



## Typical Electrical Characteristics (cont.)

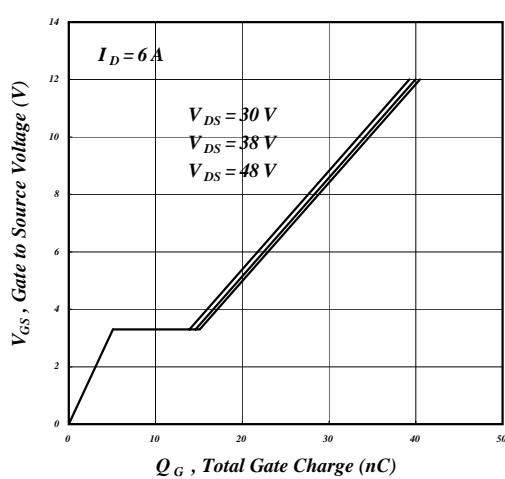


Fig 7. Gate Charge Characteristics

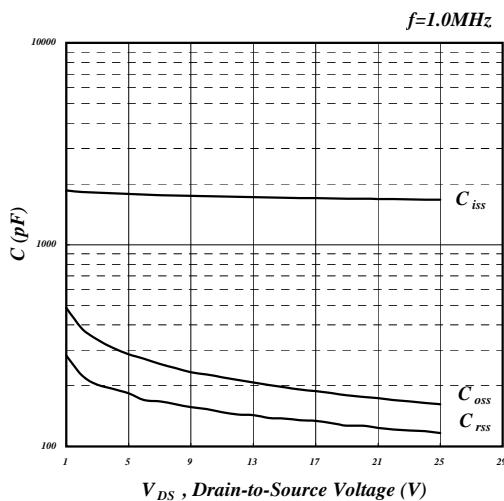


Fig 8. Typical Capacitance Characteristics

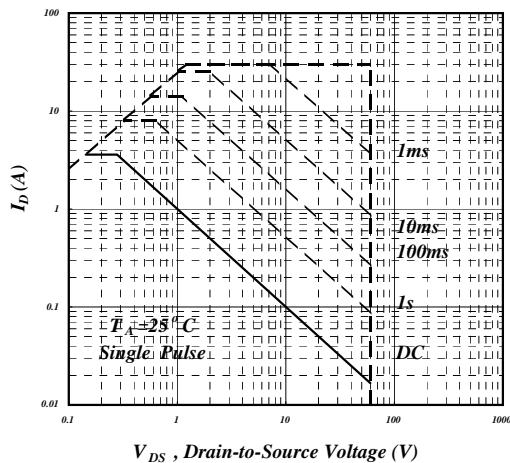


Fig 9. Maximum Safe Operating Area

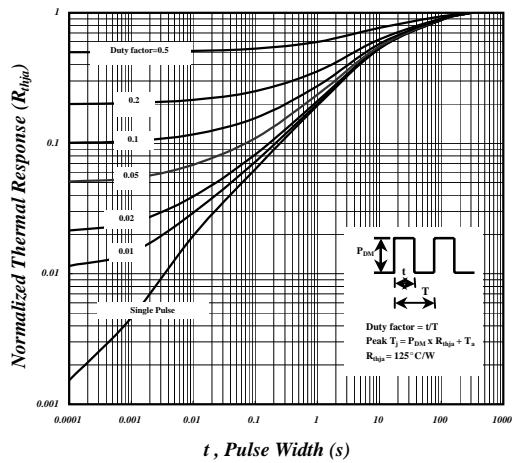


Fig 10. Effective Transient Thermal Impedance

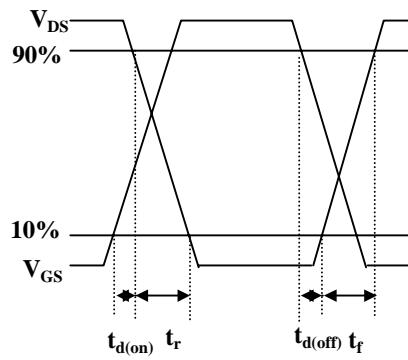


Fig 11. Switching Time Waveform

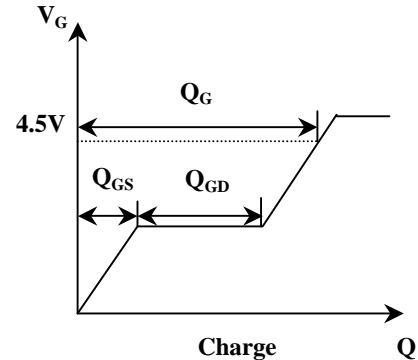
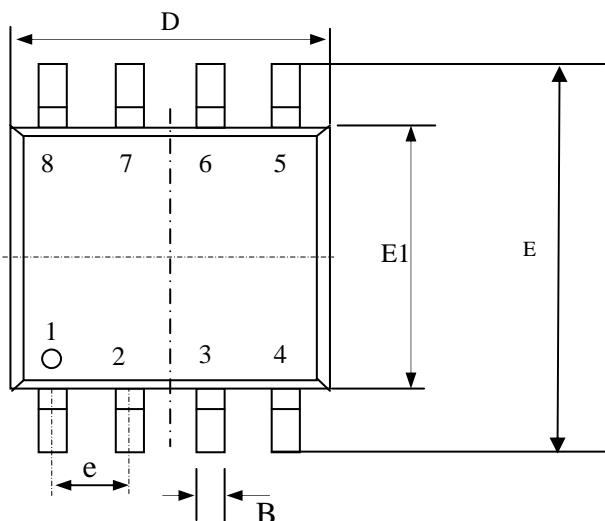


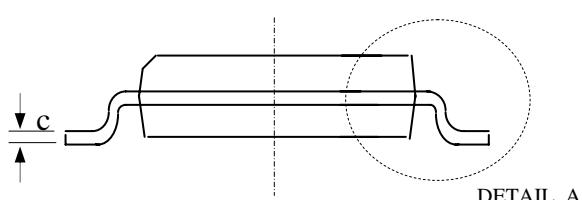
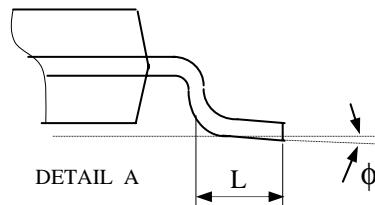
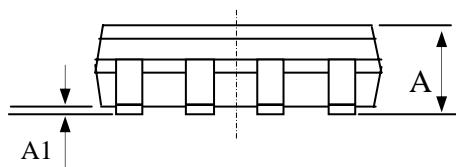
Fig 12. Gate Charge Waveform



## Package Dimensions: SO-8

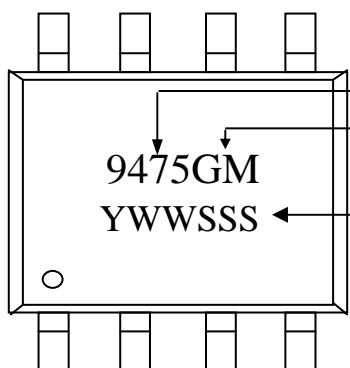


SYMBOLS	Millimeters		
	MIN	NOM	MAX
A	1.35	1.55	1.75
A1	0.10	0.18	0.25
B	0.33	0.41	0.51
C	0.19	0.22	0.25
D	4.80	4.90	5.00
E1	3.80	3.90	4.00
E	5.80	6.15	6.50
L	0.38	0.71	1.27
φ	0	4.00	8.00
e	1.27 TYP		



1. All dimensions are in millimeters.
2. Dimensions do not include mold protrusions.

## Marking Information: SO-8



Product: AP9475  
Package:  
GM = RoHS-compliant SO-8  
Date/lot code (YWWSSS)  
Y: Last digit of the year  
WW: Work week  
SSS: Lot code sequence